

## 150V N-Channel Enhancement Mode Power MOSFET

# **Description**

WML071N15HG2 uses Wayon's 2<sup>nd</sup> generation power trench MOSFET technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance. This device is well suited for high efficiency fast switching applications.

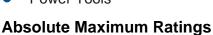


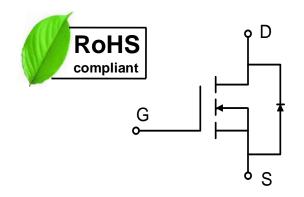
#### **Features**

- $V_{DS}$ = 150V,  $I_D$  = 120A  $R_{DS(on)}$  < 7.1m $\Omega$  @  $V_{GS}$  = 10V
- High Speed Power Switching
- Low Gate Charge
- Low R<sub>DS(ON)</sub>
- 100% EAS Guaranteed

# **Applications**

- Synchronous Rectification in SMPS
- Hard Switching and High Speed Circuit
- UPS
- Motor Control
- Power Tools





Parameter		Symbol	Value	Unit	
Drain-Source Voltage		V <sub>DS</sub>	150	V	
Gate-Source Voltage		V <sub>GS</sub>	±20	V	
Continuous Drain Current <sup>1</sup>	T <sub>C</sub> =25°C		120	Δ.	
Continuous Drain Current	T <sub>C</sub> =100°C	l <sub>D</sub>	90	A	
Pulsed Drain Current <sup>2</sup>		I <sub>DM</sub>	430	А	
Single Pulse Avalanche Energy <sup>3</sup>		EAS	405	mJ	
Avalanche Current		las	45	А	
Total Power Dissipation <sup>4</sup> T <sub>C</sub> =25°C		P <sub>D</sub>	272.7	W	
Operating Junction and Storage Temperature Range		Тл, Тата	-55 to 175	°C	

#### **Thermal Characteristics**

Parameter	Symbol	Value	Unit	
Thermal Resistance from Junction-to-Ambient <sup>1</sup>	Reja	61		
Thermal Resistance from Junction-to-Case <sup>1</sup>	R <sub>θJC</sub>	0.55	°C/W	



## Electrical Characteristics T<sub>c</sub> = 25°C, unless otherwise noted

Parameter		Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static Characteristics					I	l	I
Drain-Source Breakdown Voltage		V <sub>(BR)DSS</sub>	$V_{GS} = 0V, I_D = 250\mu A$	150	-	-	V
Gate-body Leakage current		lgss	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
Zeio Gale vollage Dialii	TJ=25°C	I <sub>DSS</sub>	V <sub>DS</sub> = 150V, V <sub>GS</sub> = 0V	-	-	1	μA
Current .	T <sub>J</sub> =100°C	1033	VD3 = 100V, VG3 = 0V	-	-	100	
Gate-Threshold Voltage		$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2	-	4	V
Drain-Source on-Resistance <sup>2</sup>		R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	-	6.4	7.1	mΩ
Forward Transconductance <sup>2</sup>		<b>g</b> fs V <sub>DS</sub> = 5V, I <sub>D</sub> =20A		-	76	-	S
Dynamic Characteristics							
Input Capacitance		Ciss		-	5270	-	pF
Output Capacitance		Coss	V <sub>DS</sub> = 75V, V <sub>GS</sub> =0V, f =1MHz	-	392	-	
Reverse Transfer Capacitance		C <sub>rss</sub>		-	17	-	
Switching Characteristics	·						
Gate Resistance		Rg	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz	-	2.9	-	Ω
Total Gate Charge		Qg			69	-	nC
Gate-Source Charge Gate-Drain Charge		Q <sub>gs</sub>	$V_{GS} = 10V, V_{DS} = 75V, I_{D} = 20A$	-	22	-	
		$\mathbf{Q}_{gd}$		-	10	-	
Turn-on Delay Time  Rise Time  Turn-off Delay Time  Fall Time		t <sub>d(on)</sub>	$V_{GS} = 10V, V_{DS} = 75V, R_G = 10\Omega,$	-	20	-	nS
		t <sub>r</sub>		-	19.5	-	
		t <sub>d(off)</sub>	I <sub>D</sub> = 20A	-	35	-	
		tf		-	13	-	
Drain-Source Body Diode	Characte	eristics					
Diode Forward Voltage <sup>2</sup>		V <sub>SD</sub>	I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V	-	-	1.0	V
Continuous Source Current <sup>1,5</sup>		ls	V <sub>G</sub> = V <sub>D</sub> = 0V , Force Current	-	-	120	Α
Body Diode Reverse Recovery Time		t <sub>rr</sub>	V <sub>R</sub> = 75V ,I <sub>F</sub> = 20A,	-	82	-	nS
Body Diode Reverse Recovery Charge		Q <sub>rr</sub>	dl/dt = 100A/µs	-	160	-	nC

#### Notes:

- 1.The data tested by surface mounted on a 1 inch2 FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.4mH,  $I_{AS}$ =45A
- 4.The power dissipation is limited by 175°C  $\,$  junction temperature
- 5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



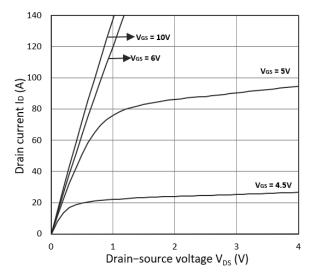


Figure 1. Output Characteristics

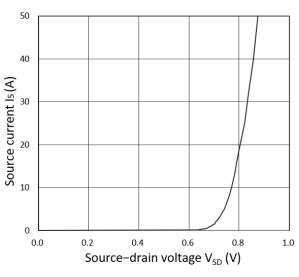


Figure 3. Forward Characteristics of Reverse

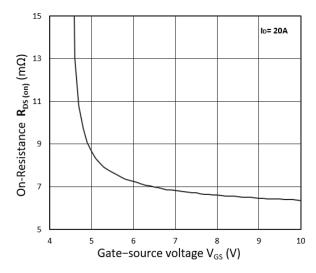


Figure 5.  $R_{DS(ON)}$  vs.  $V_{GS}$ 

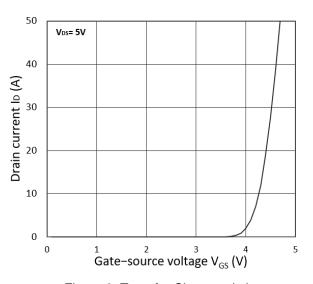


Figure 2. Transfer Characteristics

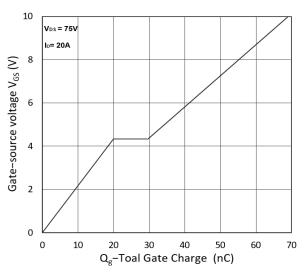


Figure 4. Gate Charge Characteristics

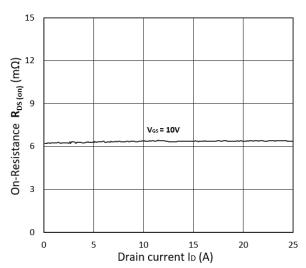
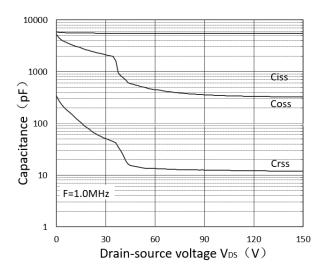


Figure 6. RDS(ON) vs. ID





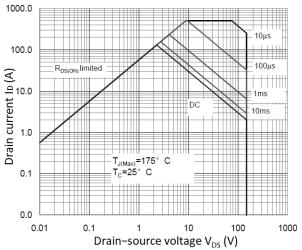


Figure 7. Capacitance Characteristics

Figure 8. Safe Operating Area

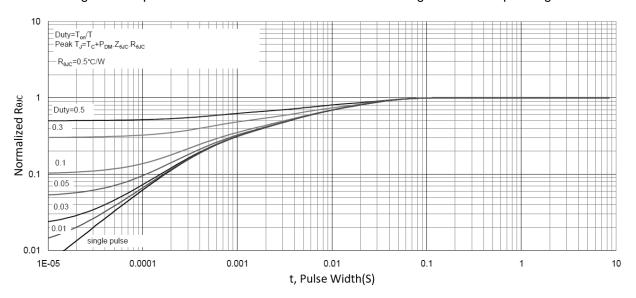


Figure 9. Normalized Maximum Transient Thermal Impedance

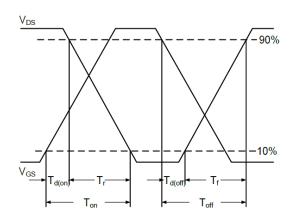


Figure 10. Switching Time Waveform

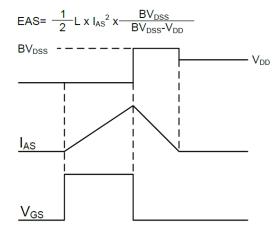
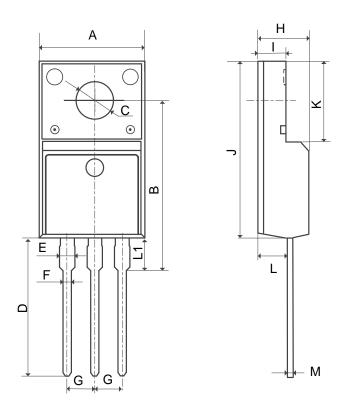


Figure 11. Unclamped Inductive Switching

Waveform



## **Mechanical Dimensions for TO-220F**



## **COMMON DIMENSIONS**

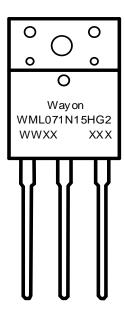
	MM			
SYMBOL	MIN	MAX		
А	9.96	10.36		
В	15.10	16.10		
С	3.03	3.38		
D	12.64	13.38		
E	1.18	1.58		
F	0.65	0.95		
G	2.54REF			
Н	4.50	4.90		
I	2.34	2.74		
J	15.57	16.17		
K	6.70REF			
L	2.56	2.96		
M	0.40	0.60		
L1	2.85	3.50		



## **Ordering Information**

Part	Package	Marking	Packing method
WML071N15HG2	TO-220F	WML071N15HG2	Tube

## **Marking Information**



WML071N15HG2 = Device code

WWXX XXX= Date code

#### **Contact Information**

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For additional information, please contact your local Sales Representative.

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